

SOT2012-1

LFBGA164, low profile fine-pitch ball grid array package, 164 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.146 mm body

4 November 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA164
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	03-10-2019
Manufacturer package code	98ASA01391D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.85	8	8.15	mm
package width	7.85	8	8.15	mm
package height	-	1.146	1.23	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	164	-	



LFBGA164, low profile fine-pitch ball grid array package, 164 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.146 mm body

2 Package outline

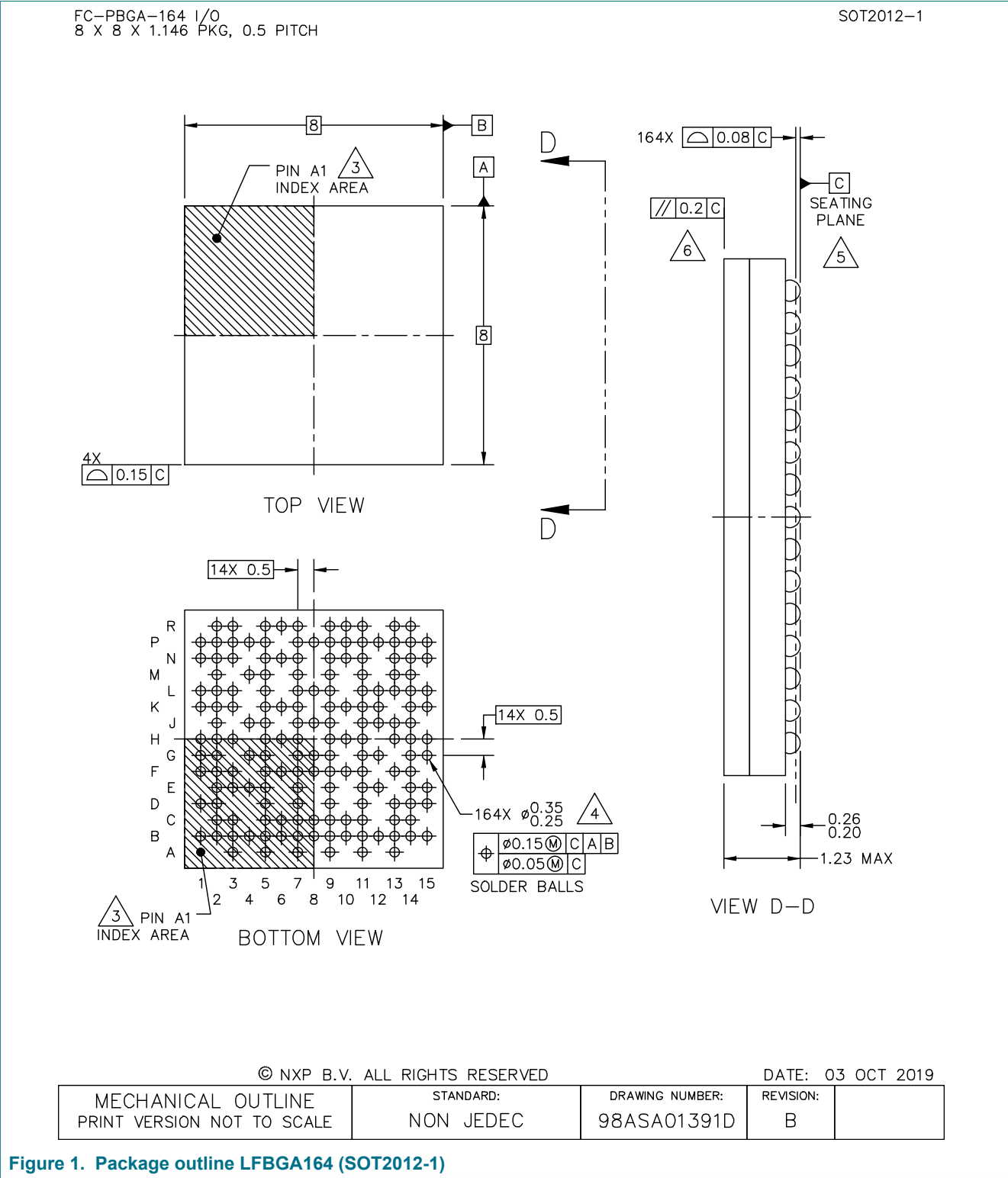
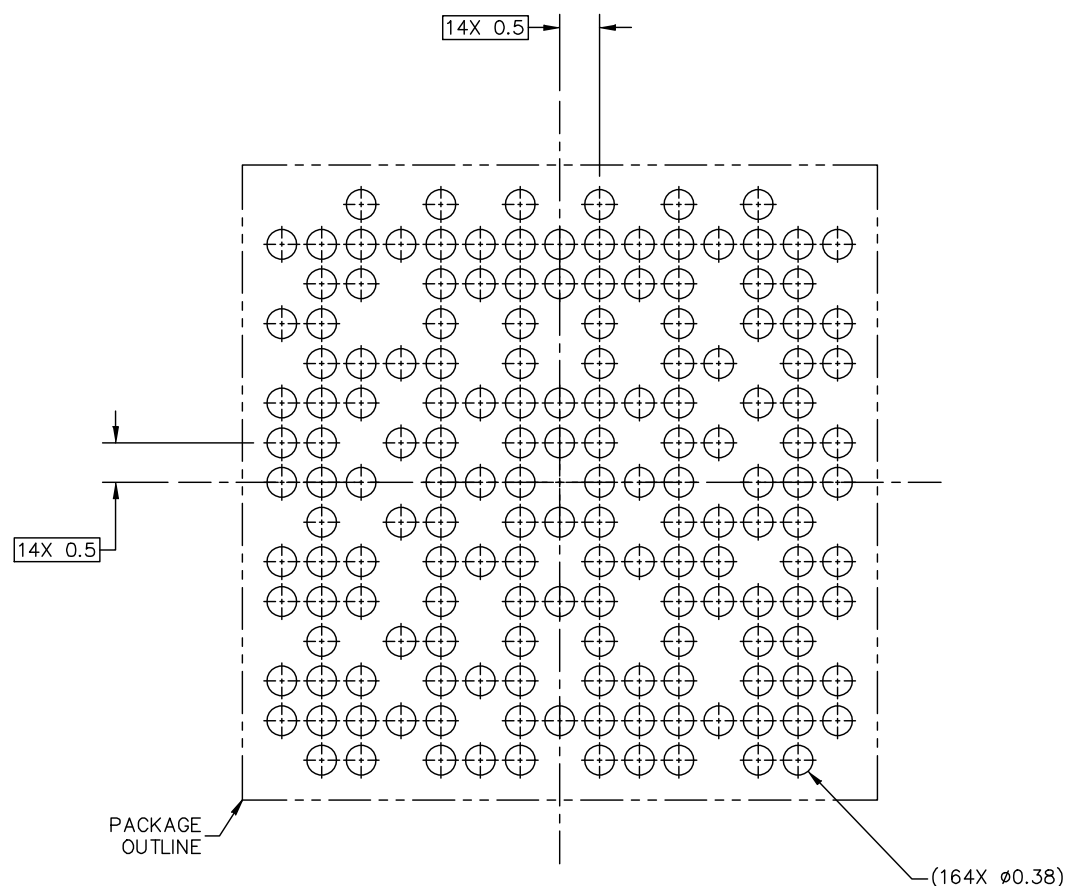


Figure 1. Package outline LFBGA164 (SOT2012-1)

3 Soldering

FC-PBGA-164 I/O
8 X 8 X 1.146 PKG, 0.5 PITCH

SOT2012-1



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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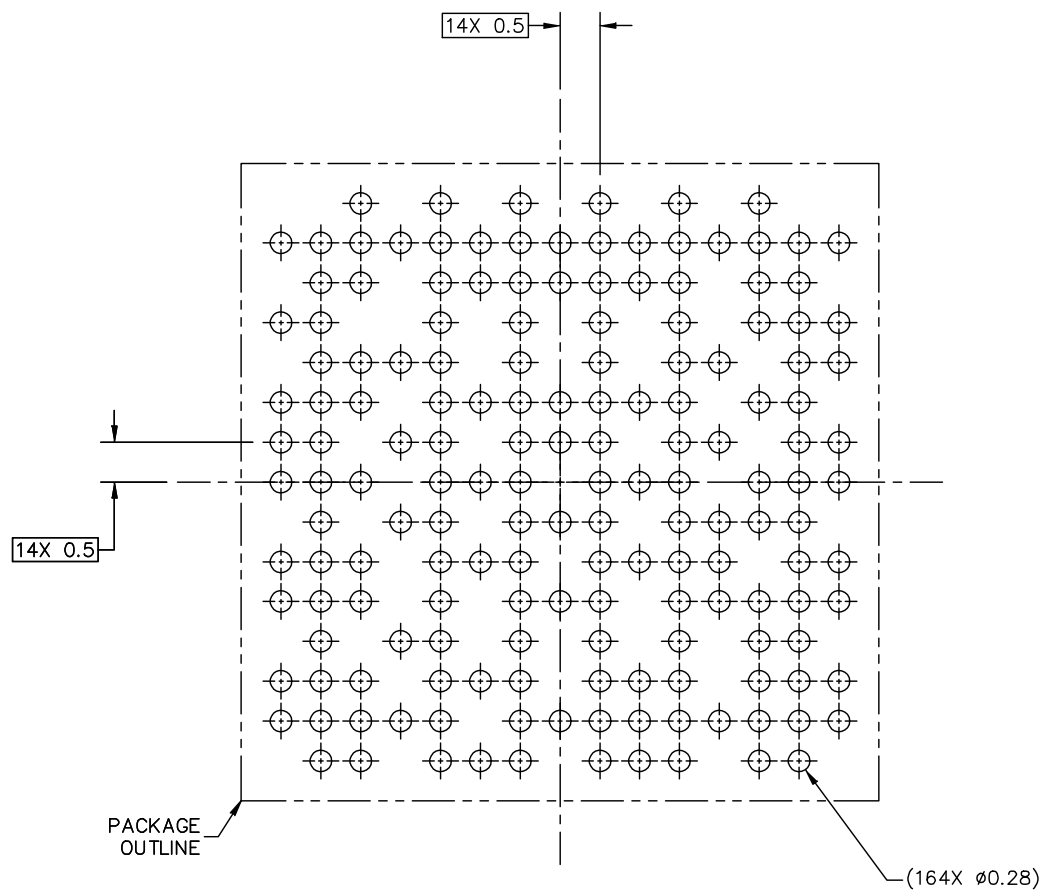
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01391D	REVISION: B
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Figure 2. Reflow soldering footprint part1 for LFBGA164 (SOT2012-1)

LFBGA164, low profile fine-pitch ball grid array package, 164 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.146 mm body

FC-PBGA-164 I/O
8 X 8 X 1.146 PKG, 0.5 PITCH

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

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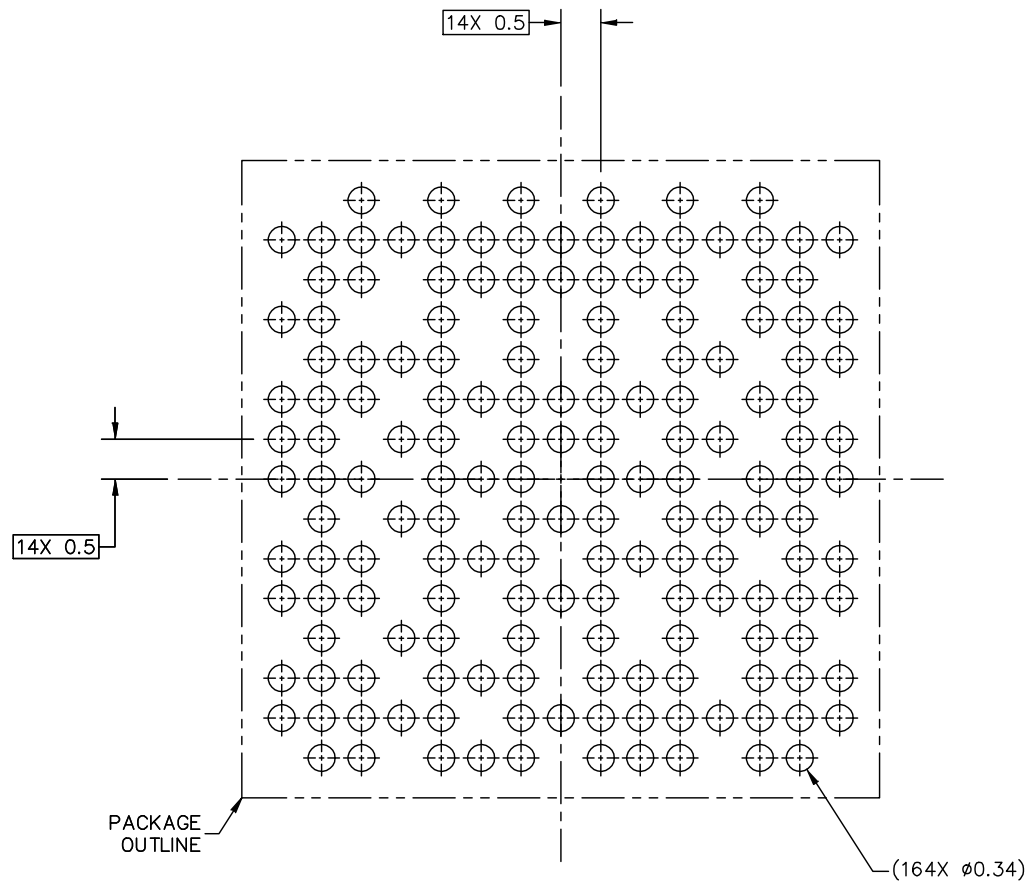
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01391D	REVISION: B	
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Figure 3. Reflow soldering footprint part2 for LFBGA164 (SOT2012-1)

LFBGA164, low profile fine-pitch ball grid array package, 164 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.146 mm body

FC-PBGA-164 I/O
8 X 8 X 1.146 PKG, 0.5 PITCH

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for LFBGA164 (SOT2012-1)

LFBGA164, low profile fine-pitch ball grid array package, 164 terminals, 0.5 mm pitch, 8 mm x 8 mm x 1.146 mm body

FC-PBGA-164 I/O
8 X 8 X 1.146 PKG, 0.5 PITCH

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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note LFBGA164 (SOT2012-1)

4 Legal information

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